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**STI Electronics, Inc. Awarded Patent for Imbedded Component Die Technology**



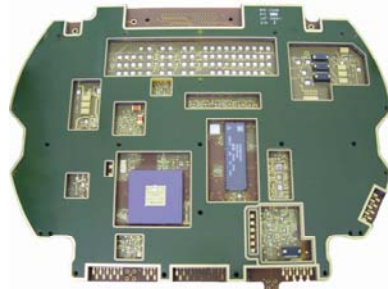
From Left to right: Mark McMeen, Casey Copper, Jim Raby, Ellen Raby, & David Raby

Madison, Alabama, December 6, 2006 - STI Electronics, Inc. (STI), a premier full-service electronics organization, announces that it has been awarded a patent for its Imbedded Component Die Technology (IC/DT). This technology involves the use of integrated circuit components that are imbedded within a laminate substrate disposed on a thermally conductive core, which provides a thermal sink. The circuit components are electrically connected to the integrated circuit via flexible electrical interconnects such as flexible wire bonds. An electronically insulating coating covers the exposed surfaces and provides rigidity preventing contamination of the integrated circuit assembly. In addition, a thermally

conductive encapsulating material, such as a silicon gel, encases the circuit components providing additional mechanical support, a second environmental barrier and a thermal sink for the dissipation of heat.

This process improves the performance and rigidity of integrated circuits under extreme conditions such as temperature, vibration and g-force. The patent was applied for on May 23, 2003 and was awarded on October 3, 2006.

The full text and images of the IC/DT patent, U.S. 7,116,557 are available at [www.uspto.gov](http://www.uspto.gov) by doing a patent number search under issued patents.





### **About STI Electronics, Inc.**

Established in 1982, STI Electronics, Inc. is the premier full service organization for training, laboratory analysis, prototyping, and small to medium volume PCB assembly in the electronics industry. STI also produces a complete line of solder training kits and training support products many in lead free versions. In addition, STI is an Approved IPC Training and Certification Center for IPC-A-600, IPC-A-610, J-STD-001, IPC-7711/7721 and IPC-A-620 as well as distribute for over 90 different product lines including Kester, JBC, Tech Spray, etc.

Jim D. Raby, founder and Technical Director of STI, has over fifty years of experience in the industry including development of the NASA and Department of Defense Specifications. Jim has been very instrumental in keeping STI abreast of upcoming technological changes and future needs of the industry. Jim also initiated the IC/DT concept and has lead the research and development phase of the project. David Raby, President and CEO of STI, is currently serving a second two-year term as President of the Surface Mount Technology Association (SMTA). He also served for six years on the SMTA Board of Directors.

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